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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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MCH6663

Power MOSFET 30V, 188mΩ, 1.8A, -30V, 325mΩ, -1.5A, **Complementary Dual**

Features

• ON-Resistance Nch : $R_{DS}(on)1=145m\Omega$ (typ)

Pch : $R_{DS}(on)1=250m\Omega$ (typ)

- 4V Drive
- Complementary N-Channel and P-Channel MOSFET
- Pb-Free, Halogen Free and RoHS Compliance

Specifications

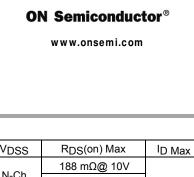
Absolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	N-channel	P-channel	Unit
Drain to Source Voltage	V _{DSS}	30	-30	V
Gate to Source Voltage	V _{GSS}	±20	±20	V
Drain Current (DC)	ID	1.8	-1.5	А
Drain Current (Pulse) PW≤10μs, duty cycle≤1%	I _{DP}	7.2	-6	А
Power Dissipation When mounted on ceramic substrate (900mm ² ×0.8mm) 1unit	PD	0.8		W
Junction Temperature	Tj	150		°C
Storage Temperature	Tstg	-55 to +150		°C

This product is designed to "ESD immunity < 200V*", so please take care when handling. * Machine Model

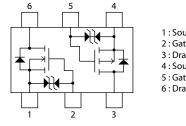
Thermal Resistance Ratings

Parameter	Symbol	Value	Unit
Junction to Ambient When mounted on ceramic substrate (900mm ² ×0.8mm) 1unit	R _{θJA}	156.25	°C/W

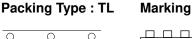


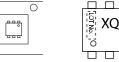
VDSS	R _{DS} (on) Max	ID Max
NL OF	188 mΩ@ 10V	
N-Ch 30V	343 mΩ@ 4.5V	1.8A
	378 mΩ@ 4V	
P-Ch –30V	325 mΩ@ –10V	
	555 mΩ@ –4.5V	-1.5A
	641 mΩ@ –4V	











Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

MCH6663

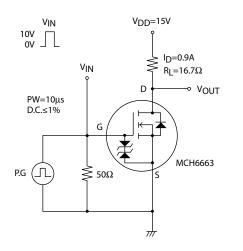
Electrical Characteristics at $Ta = 25^{\circ}C$

Parameter	Symbol	Conditions		Value		
Falalletei	Symbol	Symbol Conditions		typ	max	Unit
[N-channel]						
Drain to Source Breakdown Voltage	V(BR)DSS	I _D =1mA, V _{GS} =0V	30			V
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =30V, V _{GS} =0V			1	μA
Gate to Source Leakage Current	IGSS	V _{GS} =±16V, V _{DS} =0V			±10	μA
Gate Threshold Voltage	V _{GS} (th)	V _{DS} =10V, I _D =1mA	1.2		2.6	V
Forward Transconductance	9FS	V _{DS} =10V, I _D =0.9A		1.1		S
Static Drain to Source On-State Resistance	R _{DS} (on)1	I _D =0.9A, V _{GS} =10V		145	188	mΩ
	R _{DS} (on)2	I _D =0.5A, V _{GS} =4.5V		245	343	mΩ
	R _{DS} (on)3	I _D =0.5A, V _{GS} =4V		270	378	mΩ
Input Capacitance	Ciss			88		pF
Output Capacitance	Coss	V _{DS} =10V, f=1MHz		19		pF
Reverse Transfer Capacitance	Crss			11		pF
Turn-ON Delay Time	t _d (on)			3.4		ns
Rise Time	tr	1		3.6		ns
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit		10.5		ns
Fall Time	tf	7		4.0		ns
Total Gate Charge	Qg			2.0		nC
Gate to Source Charge	Qgs	V _{DS} =15V, V _{GS} =10V, I _D =1.8A		0.33		nC
Gate to Drain "Miller" Charge	Qgd	7		0.29		nC
Forward Diode Voltage	V _{SD}	I _S =1.8A, V _{GS} =0V		0.86	1.2	V
[P-channel]						
Drain to Source Breakdown Voltage	V(BR)DSS	I _D =-1mA, V _{GS} =0V	-30			V
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =-30V, V _{GS} =0V			-1	μA
Gate to Source Leakage Current	IGSS	V _{GS} =±16V, V _{DS} =0V			±10	μΑ
Gate Threshold Voltage	V _{GS} (th)	V _{DS} =-10V, I _D =-1mA	-1.2		-2.6	V
Forward Transconductance	9FS	V _{DS} =-10V, I _D =-0.8A		1.3		S
	R _{DS} (on)1	I _D =-0.8A, V _{GS} =-10V		250	325	mΩ
Static Drain to Source On-State Resistance	R _{DS} (on)2	I _D =-0.4A, V _{GS} =-4.5V		397	555	mΩ
	R _{DS} (on)3	I _D =-0.4A, V _{GS} =-4V		458	641	mΩ
Input Capacitance	Ciss			82		pF
Output Capacitance	Coss	V _{DS} =-10V, f=1MHz		22		pF
Reverse Transfer Capacitance	Crss			16		pF
Turn-ON Delay Time	t _d (on)			4.0		ns
Rise Time	tr			3.3		ns
Turn-OFF Delay Time	t _d (off)	See specified Test Circuit		12		ns
Fall Time	t _f			5.4		ns
Total Gate Charge	Qg			2.2		nC
Gate to Source Charge	Qgs	V _{DS} =-15V, V _{GS} =-10V, I _D =-1.5A		0.36		nC
Gate to Drain "Miller" Charge	Qgd]		0.49		nC
Forward Diode Voltage	V _{SD}	IS=-1.5A, VGS=0V		-0.9	-1.5	V

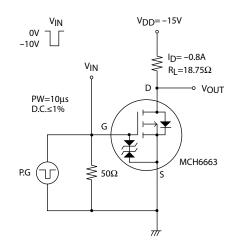
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

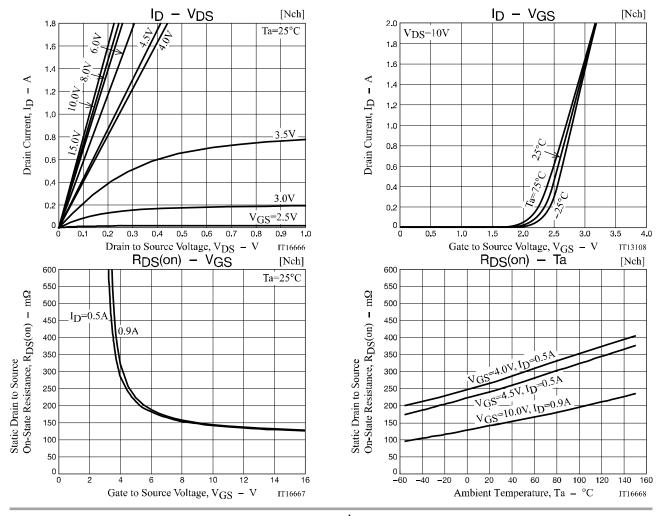
Switching Time Test Circuit

[N-channel]

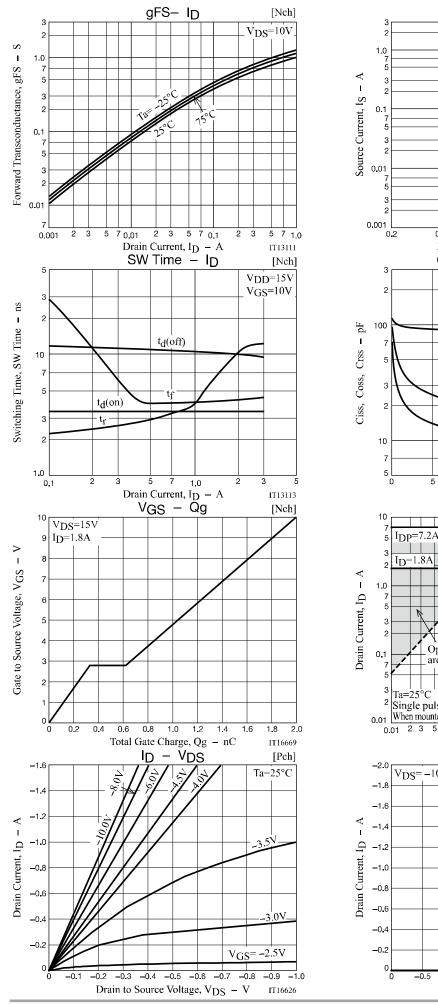


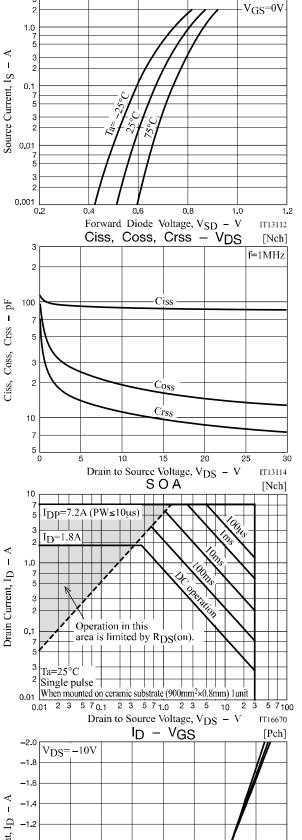
[P-channel]





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-3.5

-4.0

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-2.5

-1.0

-1.5

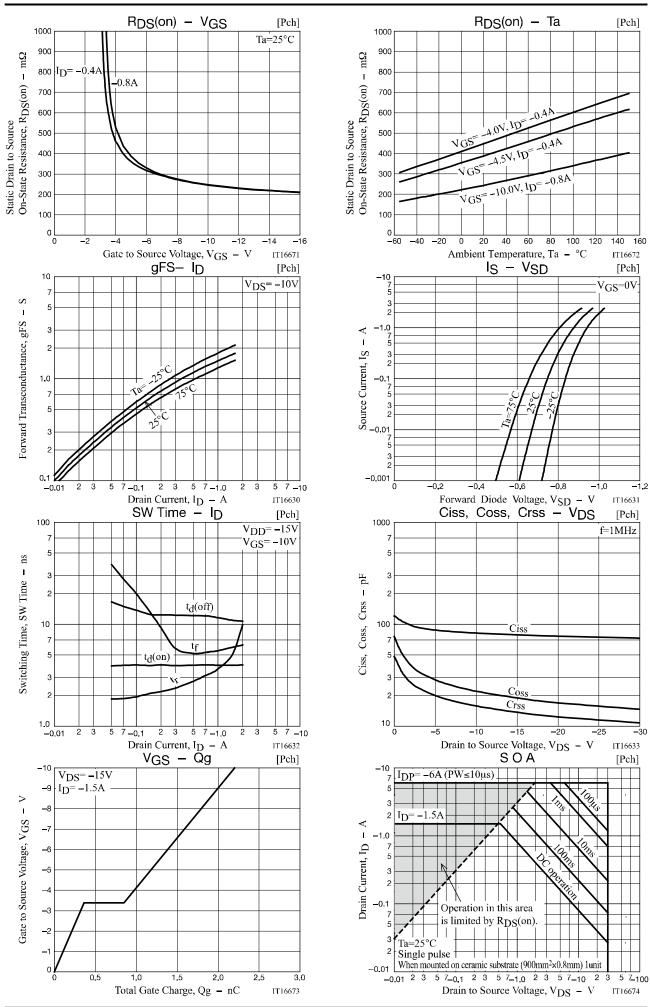
-2.0

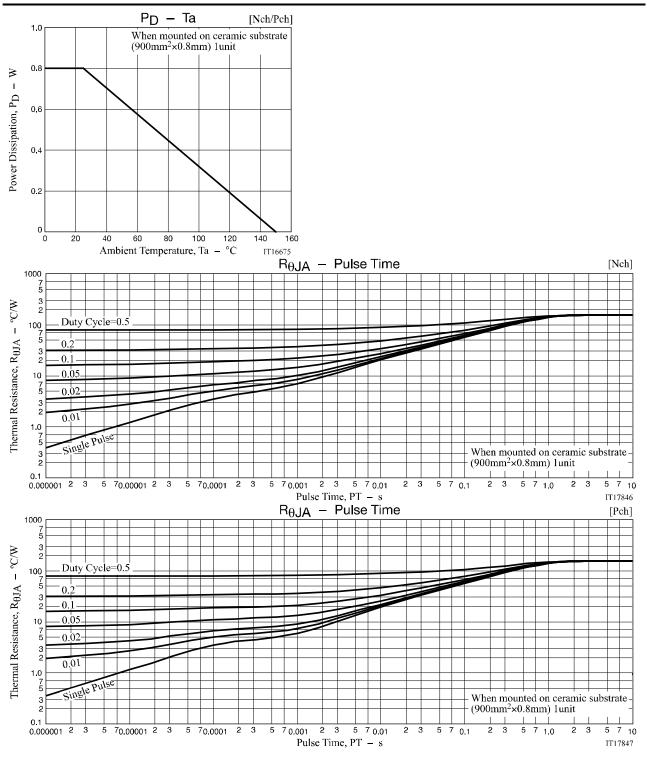
Gate to Source Voltage, V_{GS} – V

 $I_{S} - V_{SD}$

[Nch]

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Package Dimensions

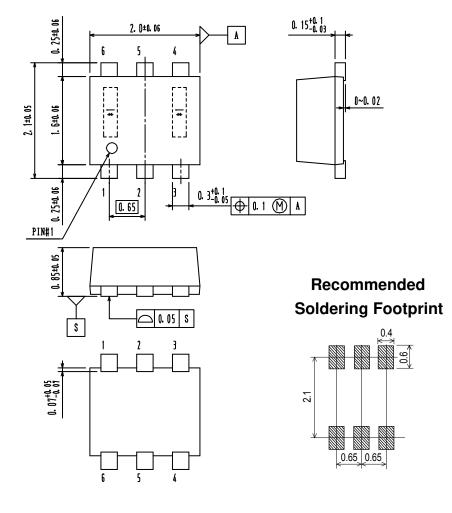
MCH6663-TL-H / MCH6663-TL-W

MCPH6

CASE 419AS ISSUE O

unit : mm

- 1 : Source1
- 2 : Gate1
- 3 : Drain2
- 4 : Source2
- 5 : Gate 2
- 6 : Drain1



ORDERING INFORMATION

Device	Package	Shipping	Note	
MCH6663-TL-H	MCPH6	3,000 pcs. / Tape & Reel	Pb-Free and Halogen Free	
MCH6663-TL-W	SC-88,SC-70-6,SOT-363	3,000 pcs. / Tape & Reel		

Note on usage : Since the MCH6663 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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